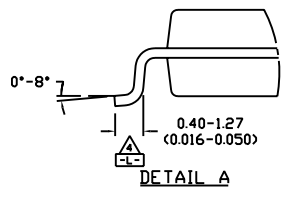
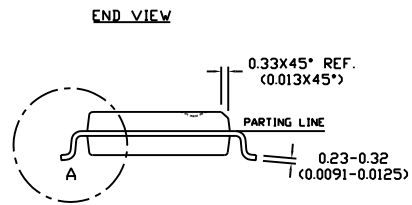
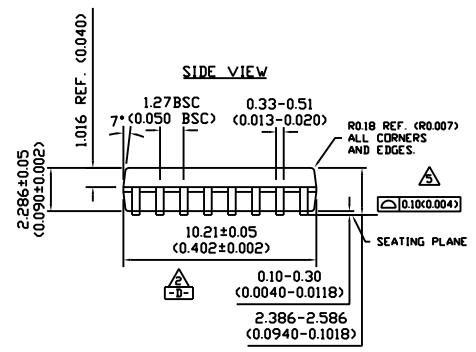
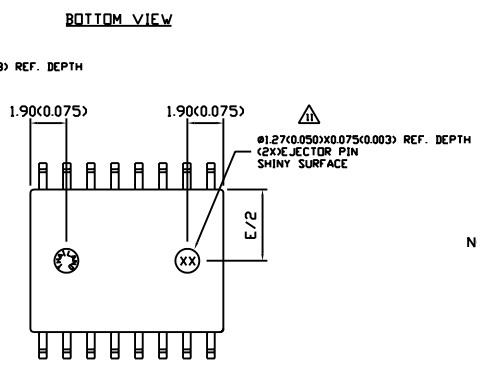
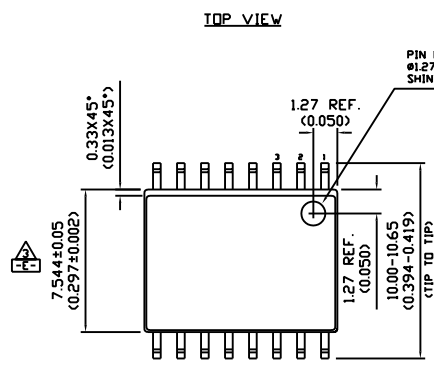


| REV | DESCRIPTION | DATE |
|-----|----------------|-----------|
| A | ORIGINAL ISSUE | JUN 23'00 |
| | | |
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NOTES

- DIMENSIONING & TOLERANCING PER ANSI.Y14.5M-1982
- DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED 0.15 MM (0.006") PER SIDE.
- DIMENSION "E" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM (0.010") PER SIDE.
- "L" IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE
- FORMED LEADS SHALL BE PLANED WITH RESPECT TO ONE ANOTHER WITHIN 0.10 MM (0.004") AT SEATING PLANE.
- BODY FINISH : 21 - 24 CHARMILLES.
- CONTROLLING DIMENSION : MILLIMETER CONVERTED INCH ARE NOT NECESSARILY EXACT.
- LEAD FINISH WILL BE ELECTROPLATING WITH A THICKNESS OF 300-800 MICROINCHES.
- CHARACTER HEIGHT ON EJECTOR PIN "xx" IS 0.635MM(0.025")
"xx" IS STAND FOR MOLD CAVITY NUMBER.(01,02,03,.....99)
- ALL TOLERANCE UNLESS OTHERWISE SPECIFIED ±0.05MM(±0.002")
- RAISED CHARACTER NOT TO PROTRUDE BEYOND SURFACE OF PACKAGE BODY.
- THE LEAD WIDTH, AS MEASURED 0.36MM(0.014") OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAX. VALUE OF 0.61MM(0.024")



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|------------------------------|--|
| DRAWN BY: ANUPHAB U. | TITLE: 16L SOIC PKG. OUTLINE DWG. 300 MIL BODY WIDTH FAMILY (MGP MOLD) |
| CHECKED BY: NATAPORN C. | |
| APPROVED BY: THANAPONG I. | DATE : JUN 23'00 |
| APPROVED BY: VIRAT T. | REF. NO. : JEDEC MS-013 |

| | |
|---------------------------|----------------------|
| DWG. NO. J016PO-01 | SCALE : NOT TO SCALE |
| REV. A | SHEET 1 OF 1 |